

**650V N-CHANNEL ENHANCEMENT MODE MOSFET**

**MAIN CHARACTERISTICS**

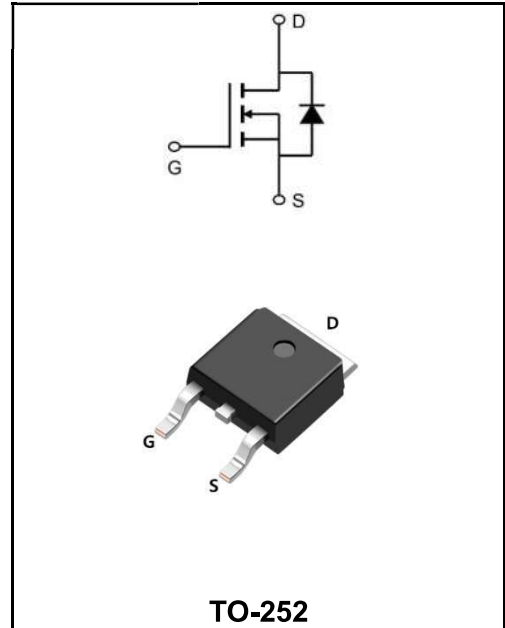
<b>I<sub>D</sub></b>	14A
<b>V<sub>DSS</sub></b>	650V <b>(Type:730V)</b>
<b>R<sub>DS(on)-typ(@V<sub>GS</sub>=10V)</sub></b>	< 650mΩ <b>(Type:560mΩ)</b>

**Features**

◆ **Is CoolFET II MOSFET**

**Application**

- ◆ Uninterruptible Power Supply(UPS)
- ◆ Power Factor Correction (PFC)



**Product Specification Classification**

Part Number	Package	Marking	Pack
YFWJ14N65AD	TO-252	YFWJ14N65AD XXXXX	2500PCS/Tape

**Maximum Ratings at T<sub>c</sub>=25°C unless otherwise specified**

Characteristics	Symbols	Value	Units
Drain-Source Voltage (V <sub>GS</sub> = 0V)	<b>V<sub>DS</sub></b>	650	<b>V</b>
Continuous Drain Current	<b>I<sub>D</sub></b>	8	<b>A</b>
Pulsed Drain Current(note1)	<b>I<sub>DM</sub></b>	14	<b>A</b>
Gate - Source Voltage	<b>V<sub>GS</sub></b>	±30	<b>V</b>
Single Pulse Avalanche Energy(note2)	<b>E<sub>AS</sub></b>	125	<b>mJ</b>
Power Dissipation(T <sub>c</sub> =25°C)	<b>P<sub>D</sub></b>	25.5	<b>W</b>
Operating Junction and Storage Temperature Range	<b>T<sub>J</sub> , T<sub>STG</sub></b>	-55 to +150	<b>°C</b>
Thermal Resistance, Junction-to-case	<b>R<sub>θJC</sub></b>	4.9	<b>°C/W</b>
Thermal Resistance, Junction ambient	<b>R<sub>θJA</sub></b>	49	<b>°C/W</b>

**Maximum Ratings at Tc=25°C unless otherwise specified**

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	$BV_{DSS}$	650	700	-	V
Breakdown voltage temperature coefficient	Reference to 25°C, $I_D=250\mu A$	$\Delta BV_{DSS}/\Delta T_J$	-	0.7	-	V/°C
Drain -Source Leakage Current	$V_{DS}=650V, V_{GS}=0V$	$I_{DSS}$	-	-	1	$\mu A$
	$V_{DS}=520V, T_C=125^\circ C$		-	-	50	
Gate to source leakage current, forward	$V_{GS}=30V, V_{DS}=0V$	$I_{GSS}$	-	-	100	nA
Gate to source leakage current, reverse	$V_{GS}=-30V, V_{DS}=0V$		-	-	-100	
Gate- Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	$V_{GS(th)}$	2.5	3.3	4.5	V
Drain to source on state resistance	$V_{GS}=10V, I_D=3.2A$	$R_{DS(ON)}$	-	560	650	mΩ
Input Capacitance	$V_{DS}=100V$ $V_{GS}=0V$ $f=1MHz$	$C_{iss}$	-	438	-	pF
Output Capacitance		$C_{oss}$	-	19.5	-	
Reverse Transfer Capacitance		$C_{rss}$	-	1.32	-	
Turn-on delay time	$V_{DS}=400V$ $I_D=3.2A$ $R_G=4.7\Omega$ $V_{GS}=10V$	$t_{d(on)}$	-	84.8	-	nS
Rising time		$T_r$	-	25.2	-	
Turn-Off Delay Time		$t_{d(OFF)}$	-	227.6	-	
Fall Time		$t_f$	-	26.8	-	
Total Gate Charge	$V_{DS}=480V$ $I_D=3.2A$ $V_{GS}=10V$	$Q_g$	-	11	-	nC
Gate-Source Charge		$Q_{gs}$	-	2.1	-	
Gate-Drain Charge		$Q_{gd}$	-	5.6	-	
Continuous source current	Integral reverse p-n Junction diode in the MOSFET	$I_S$	-	-	11	A
Pulsed source curren		$I_{SM}$	-	-	44	
Diode forward voltage drop	$I_S = 3.2A, V_{GS} = 0V$	$V_{SD}$	-	0.7	1.5	V
Reverse Recovery Time	$V_{GS} = 0V, I_S = 3.2A, V_{DS}=400V$ $diF/dt = 100A/\mu s$	$t_{rr}$	-	313	-	nS
Reverse Recovery Charge		$Q_{rr}$	-	0.877	-	uC

Note :

- 1、 The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2、 The EAS data shows Max. rating . L=0.5mH, IAS =3.2A, VDD =50V, RG=25Ω
- 3、 The test condition is Pulse Test:  $ISD \leq ID$ ,  $di/dt = 100A/us$ ,  $VDD \leq BVDSS$ , Starting at  $T_J = 25^\circ C$
- 4、 The power dissipation is limited by 150°C junction temperature
- 5、 The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Ratings and Characteristic Curves

Typical Characteristics

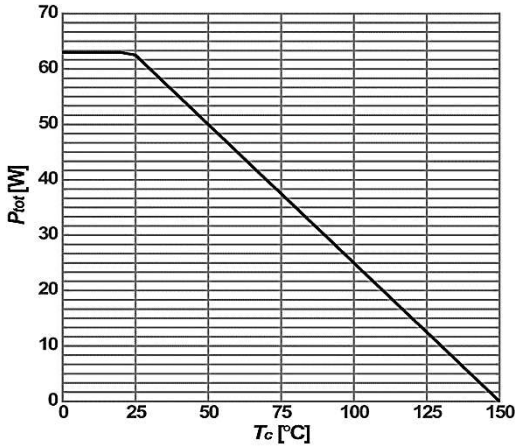


Figure1: Power dissipation (Non FullPAK)

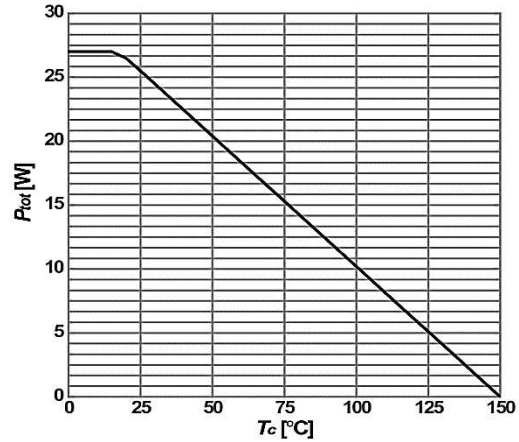


Figure2: Power dissipation (FullPAK)

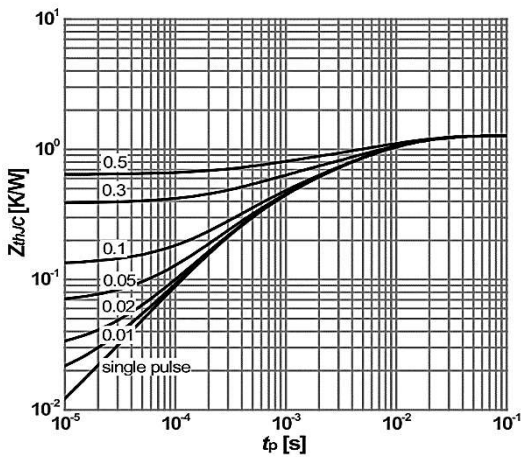


Figure3:Max. transient thermal impedance  
 $Z_{thJC}=f(t_p)$ ; parameter:  $D= t_p/T$

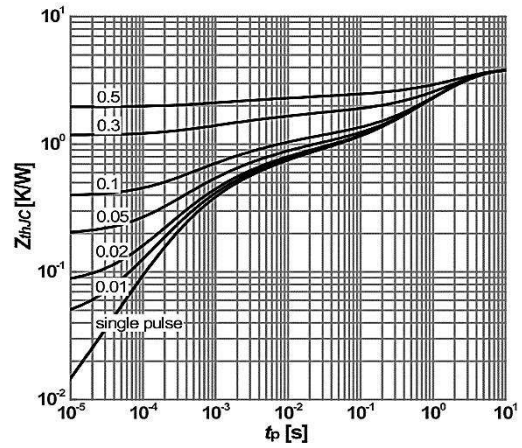


Figure4:Max. transient thermal impedance  
 $Z_{thJC}=f(t_p)$ ; parameter:  $D= t_p/T$

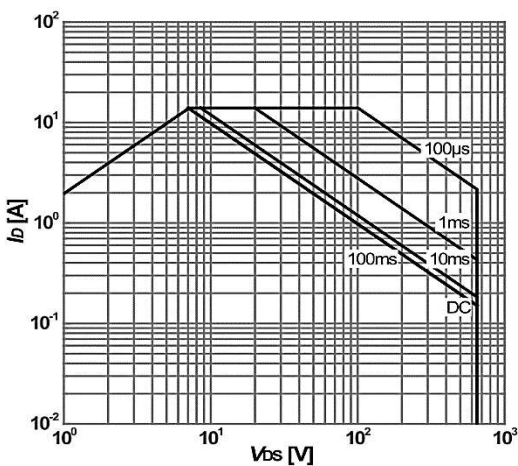


Figure5: Safe operating area (Non FullPAK)  
 $I_b=f(V_{bs})$ ;  $T_J=25^\circ\text{C}$ ;  $D=0$ ; parameter:  $t_p$

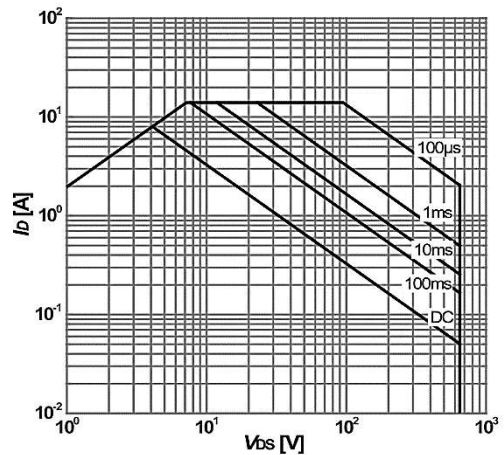
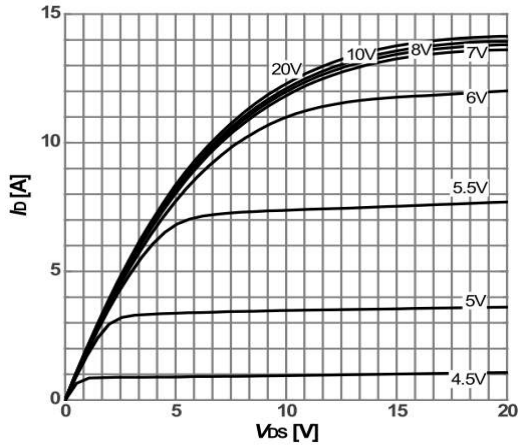
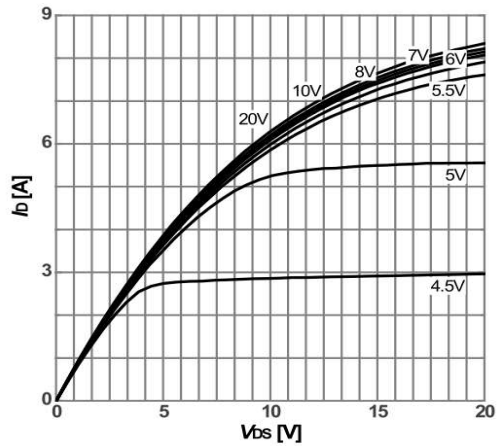


Figure6: Safe operating area (FullPAK)  
 $I_b=f(V_{bs})$ ;  $T_J=25^\circ\text{C}$ ;  $D=0$ ; parameter:  $t_p$

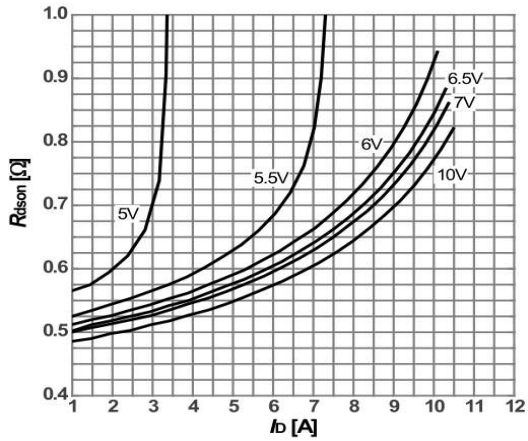
Ratings and Characteristic Curves



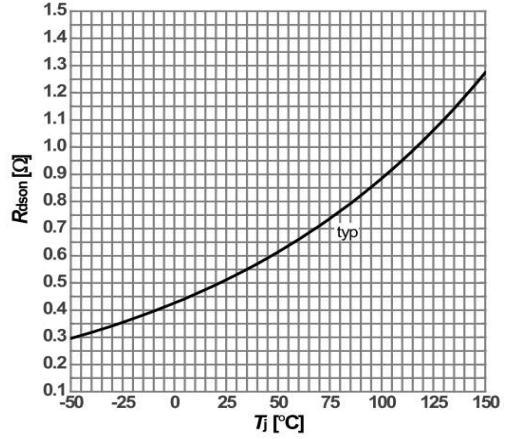
**Figure 7: Typ. output characteristics**  
 $I_D=f(V_{DS}); T_J=25^{\circ}\text{C};$  parameter:  $V_{GS}$



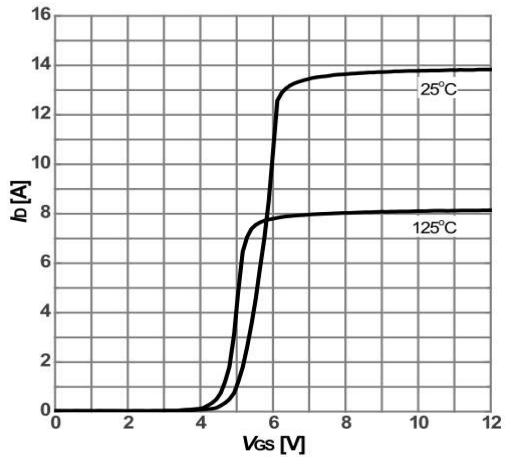
**Figure 8: Typ. output characteristics**  
 $I_D=f(V_{DS}); T_J=125^{\circ}\text{C};$  parameter:  $V_{GS}$



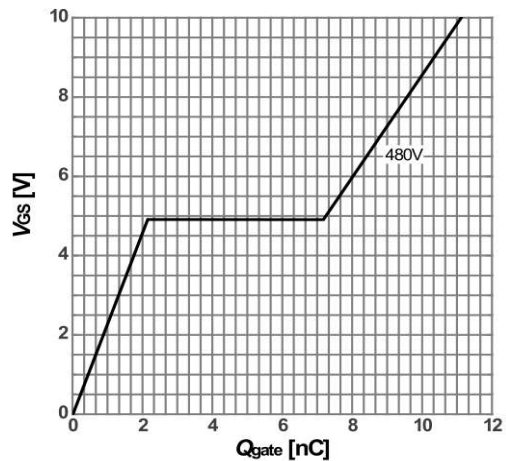
**Figure 9: Typ. drain-source on-state resistance**  
 $R_{DS(on)}=f(I_D); T_J=25^{\circ}\text{C};$  parameter:  $V_{GS}$



**Figure 10: drain-source on-state resistance**  
 $R_{DS(on)}=f(T_J); I_D=3.2\text{A}; V_{GS}=10\text{V}$



**Figure 11: Type. transfer characteristics**  
 $I_D=f(V_{GS}); V_{DS}=20\text{V};$  parameter:  $T_J$



**Figure 12: Type. gate charge**  
 $V_{GS}=f(Q_{gate}); I_D=3.2\text{A pulsed}; V_{DS}=480\text{V}$

Package Outline Dimensions Millimeters

TO-252

Dim.	Min.	Typ.	Max.
A	2.10	-	2.50
A2	0	-	0.10
B	0.66	-	0.86
B2	5.18	-	5.48
C	0.40	-	0.60
C2	0.44	-	0.58
D	5.90	-	6.30
D1	5.30REF		
E	6.40	-	6.80
E1	4.63	-	-
G	4.47	-	4.67
H	9.50	-	10.70
L	1.09	-	1.21
L2	1.35	-	1.65
V1	-	7°	-
V2	0°	-	6°
All Dimensions in millimeter			